

Data sheet

SAW filter Small cell & femtocell LTE band 8 downlink

| Series/type: | B9630 |
|----------------|------------------|
| Ordering code: | B39941B9630P810 |
| | |
| Date: | January 29, 2019 |
| Version: | 2.2 |

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RF360 Europe GmbH, Anzinger Str. 13, München, Germany



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1 Application

- Low-loss RF filter for smallcells
- Usable pass band 35MHz

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2 Features

- Package size 1.4±0.1 mm × 1.1±0.1 mm
- Package height 0.45 mm (max.)
- Approximate weight 3 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 2a (MSL2a)

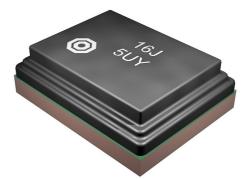
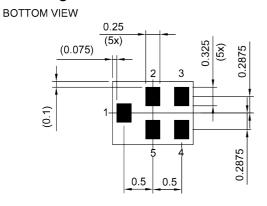


Figure 1: Picture of component with example of product marking.

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3 Package



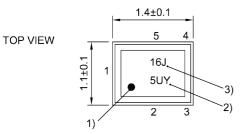
Pad and pitch tolerance ±0.05

4 Pin configuration

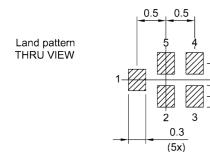
- ∎ 1 Input
- 4 Output
- 2, 3, 5 Ground

SIDE VIEW





- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number





(5X)

0.375

0.2875

0.2875

Figure 2: Drawing of package with package height A = 0.45 mm (max.). See Sec. Package information (p. 19).



5 Matching circuit

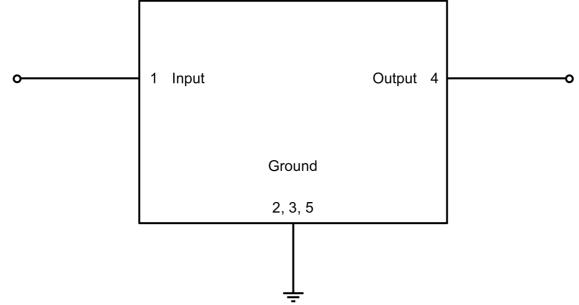


Figure 3: Schematic of matching circuit. No external matching components required.

6 Characteristics

| Temperature range for specification | T _{SPEC} | = −10 °C +85 °C |
|-------------------------------------|-------------------|-----------------|
| Input terminating impedance | Z | = 50 Ω |
| Output terminating impedance | Z _{OUT} | = 50 Ω |

| Characteristics | | | | min. for $T_{_{ m SPEC}}$ | typ. @ +25 °C | max. for $T_{\rm SPEC}$ | |
|--------------------------------|-------------|-----|---------------------------------|------------------------------|-------------------------|----------------------------|-----|
| Center frequency | | | f _c | — | 942.5 | _ | MHz |
| Maximum insertion attenuation | | | $\alpha_{_{max}}$ | | | | |
| | 925 960 | MHz | | _ | 2.1 | 3.2 | dB |
| Amplitude ripple (p-p) | | | Δα | | | | |
| | 925 960 | MHz | | — | 1.0 | 2.2 | dB |
| Maximum VSWR | | | $VSWR_{max}$ | | | | |
| @ input port | 925 960 | MHz | | _ | 1.9 | 2.3 | |
| @ output port | 925 960 | MHz | | — | 1.9 | 2.3 | |
| Maximum error vector magnitude | | | $\text{EVM}_{\text{max}}^{(1)}$ | | | | |
| | 927.4 957.6 | MHz | | _ | 2.5 | 6.0 | % |
| Minimum attenuation | | | $\alpha_{_{min}}$ | | | | |
| | 50 791 | MHz | | 40 | 43 | _ | dB |
| | 791 821 | MHz | | 43 | 46 | _ | dB |
| | 832 862 | MHz | | 40 | 49 | — | dB |
| | 880 915 | MHz | | 30 | 36 | — | dB |
| | 1570 1606 | MHz | | 35 | 52 | — | dB |
| | 1710 1785 | MHz | | 35 | 58 | — | dB |
| | 1805 1880 | MHz | | 35 | 54 | — | dB |
| | 1920 1980 | MHz | | 35 | 50 | — | dB |
| | 2110 2170 | MHz | | 35 | 46 | — | dB |
| | 2400 2500 | MHz | | 30 | 41 | — | dB |
| | 2500 2570 | MHz | | 30 | 40 | | dB |
| | 2620 2690 | MHz | | 30 | 39 | — | dB |
| | 5150 5850 | MHz | | 20 | 27 | _ | dB |

¹⁾ Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.

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| Temperature range for specification | T _{SPEC} | = −40 °C +95 °C |
|-------------------------------------|-------------------|-----------------|
| Input terminating impedance | Z | = 50 Ω |
| Output terminating impedance | Z _{OUT} | = 50 Ω |

| Characteristics | | | | min. for $T_{\rm SPEC}$ | typ. @ +25 °C | max. for $T_{_{\rm SPEC}}$ | |
|--------------------------------|-------------|-----|----------------------------------|-------------------------|-------------------------|----------------------------|-----|
| Center frequency | | | f _c | — | 942.5 | — | MHz |
| Maximum insertion attenuation | | | $\alpha_{_{max}}$ | | | | |
| | 925 960 | MHz | | _ | 2.1 | 4.2 | dB |
| Amplitude ripple (p-p) | | | Δα | | | | |
| | 925 960 | MHz | | — | 1.0 | 3.2 | dB |
| Maximum VSWR | | | $VSWR_{max}$ | | | | |
| @ input port | 925 960 | MHz | | _ | 1.9 | 2.4 | |
| @ output port | 925 960 | MHz | | — | 1.9 | 2.4 | |
| Maximum error vector magnitude | | | EVM _{max} ¹⁾ | | | | |
| | 927.4 957.6 | MHz | | _ | 2.5 | 10 | % |
| Minimum attenuation | | | $\alpha_{_{min}}$ | | | | |
| | 50 791 | MHz | | 40 | 43 | _ | dB |
| | 791 821 | MHz | | 43 | 46 | — | dB |
| | 832 862 | MHz | | 40 | 49 | — | dB |
| | 880 915 | MHz | | 26 | 36 | — | dB |
| | 1570 1606 | MHz | | 35 | 52 | — | dB |
| | 1710 1785 | MHz | | 35 | 58 | — | dB |
| | 1805 1880 | MHz | | 35 | 54 | — | dB |
| | 1920 1980 | MHz | | 35 | 50 | | dB |
| | 2110 2170 | MHz | | 35 | 46 | — | dB |
| | 2400 2500 | MHz | | 30 | 41 | — | dB |
| | 2500 2570 | MHz | | 30 | 40 | — | dB |
| | 2620 2690 | MHz | | 30 | 39 | — | dB |
| | 5150 5850 | MHz | | 20 | 27 | — | dB |

¹⁾ Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.

7 Maximum ratings

| Operable temperature | T _{oP} = −40 °C +95 °C | |
|---------------------------------------|---|---|
| Storage temperature | <i>T</i> _{STG} ¹⁾ = −40 °C +95 °C | |
| DC voltage | $ V_{\rm DC} ^{2} = 0 V$ | |
| ESD voltage | $V_{\rm ESD}^{3)} = 100 \rm V$ | Machine model. |
| Input power @ input port: 925 960 MHz | $P_{\rm iN} = 15 \rm dBm^{4)}$ | 5 MHz LTE downlink signal (25 RB) for 50000 h @ 55 °C. Source and load impedance 50Ω |

¹⁾ Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C.

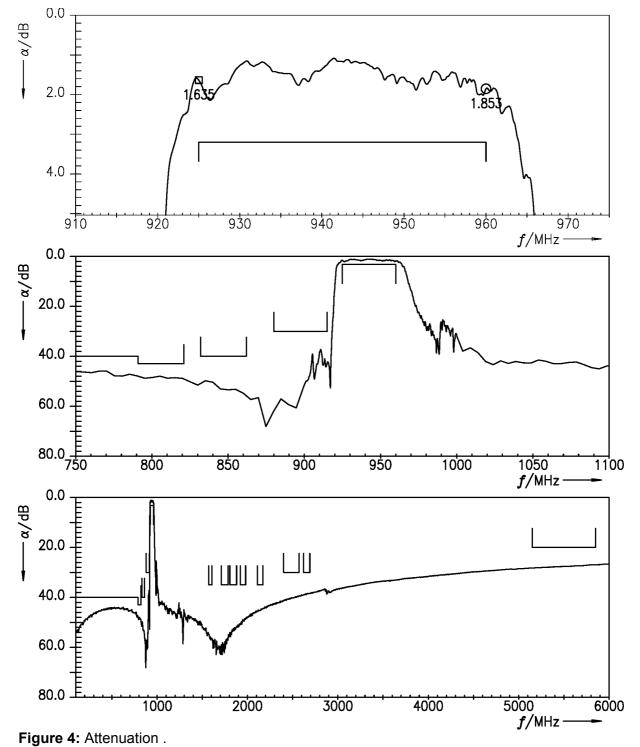
²⁾ In case of applied DC voltage blocking capacitors are mandatory.

³⁾ According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.

⁴⁾ Expected Life Time according to accelerated power durability simulation and wear out models.

8 Transmission coefficient

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□ = 925.0 O = 960.0

Z_{IN}=50 Ω

9 **Reflection coefficients**

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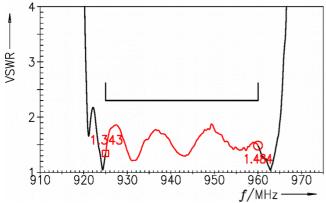


Figure 5: Reflection coefficient at input port.

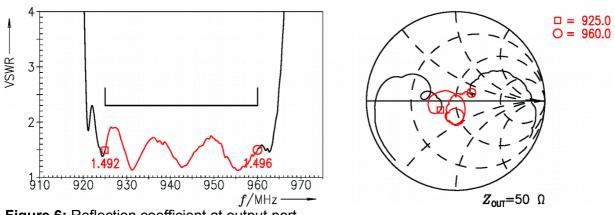


Figure 6: Reflection coefficient at output port.



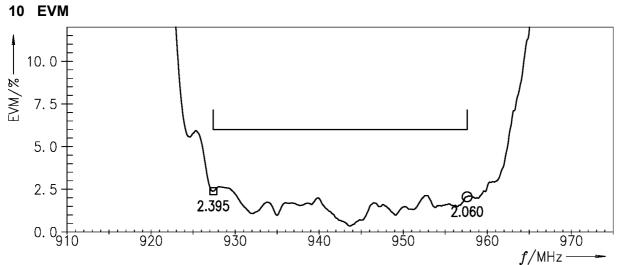
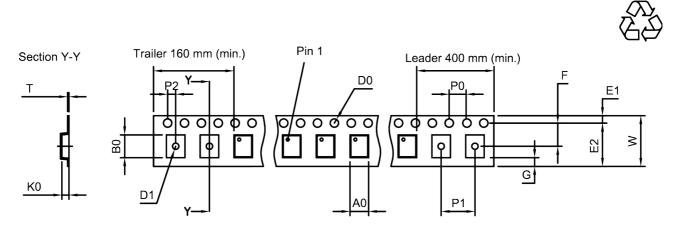


Figure 7: Error vector magnitude .



11 Packing material

11.1 Tape



User direction of unreeling

Figure 8: Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

 $\begin{array}{c} A_0 \\ B_0 \\ 1.27_{\pm 0.05} \text{ mm} \\ B_0 \\ 1.57_{\pm 0.05} \text{ mm} \\ D_0 \\ 1.5_{\pm 0.1/-0} \text{ mm} \\ D_1 \\ 0.5_{\pm 0.1} \text{ mm} \\ E_1 \\ 1.75_{\pm 0.1} \text{ mm} \end{array}$

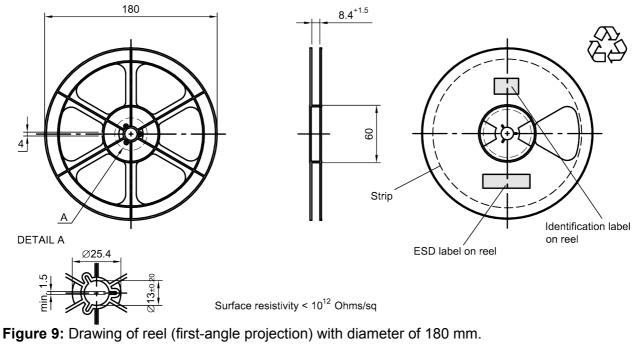
Table 1: Tape dimensions.

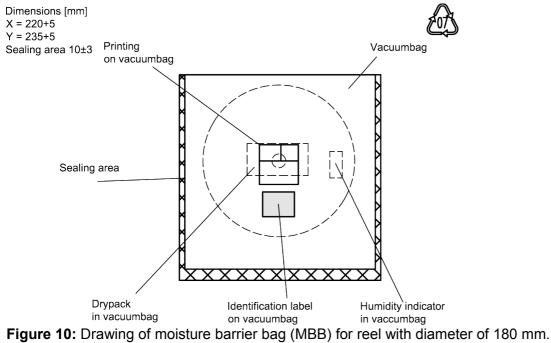
| 6.25 mm (min.) |
|----------------|
| 3.5±0.05 mm |
| 0.75 mm (min.) |
| 0.62±0.05 mm |
| 4.0±0.1 mm |
| |

| P_1 | 4.0±0.1 mm |
|-------|-----------------|
| P_2 | 2.0±0.05 mm |
| Т | 0.25±0.03 mm |
| W | 8.0+0.3/-0.1 mm |



11.2 Reel with diameter of 180 mm





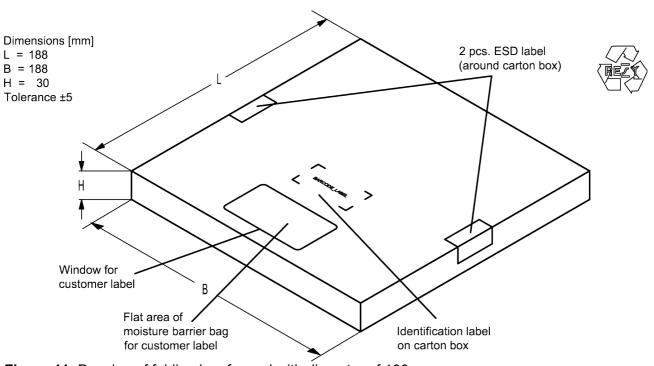


Figure 11: Drawing of folding box for reel with diameter of 180 mm.

12 Marking

Products are marked with product type number and lot number encoded according to Table 2:

■ Type number:

| The 4 digit type number is encoded by a special | e.g., B3xxxxB <u>1234</u> xxxx, | |
|---|--|---------------------------------|
| Example of decoding 16J | type number marking on device => | in decimal code. 1234 |
| | 32 ¹ + 18 (=J) x 32 ⁰ = oduct type B9630 is 9CY. | 1234 |

Lot number:

The last 5 digits of the lot number, e.g., **12345**, are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device **5UY**

5 x 47² + **27** (=U) x 47¹ + **31** (=Y) x

| evice | | in decimal code. |
|-----------------|----|------------------|
| | => | 12345 |
| 47 ⁰ | = | 12345 |

| Adopted BASE32 code for type number | | | | |
|-------------------------------------|--------|---------|--------|--|
| Decimal | Base32 | Decimal | Base32 | |
| value | code | value | code | |
| 0 | 0 | 16 | G | |
| 1 | 1 | 17 | Н | |
| 2 | 2 | 18 | J | |
| 3 | 3 | 19 | K | |
| 4 | 4 | 20 | М | |
| 5 | 5 | 21 | N | |
| 6 | 6 | 22 | Р | |
| 7 | 7 | 23 | Q | |
| 8 | 8 | 24 | R | |
| 9 | 9 | 25 | S | |
| 10 | А | 26 | Т | |
| 11 | В | 27 | V | |
| 12 | С | 28 | W | |
| 13 | D | 29 | Х | |
| 14 | E | 30 | Y | |
| 15 | F | 31 | Z | |

| Adopted BASE47 code for lot number | | | | |
|------------------------------------|----------------|------------------|----------------|--|
| Decimal value | Base47 code | Decimal value | Base47 code | |
| 0 | 0 | 24 | R | |
| 1 | 1 | 25 | S | |
| 2 | 2 | 26 | Т | |
| 3 | 3 | 27 | U | |
| 4 | 4 | 28 | V | |
| 5 | 5 | 29 | W | |
| 6 | 6 | 30 | Х | |
| 7 | 7 | 31 | Y | |
| 8 | 8 | 32 | Z | |
| 9 | 9 | 33 | b | |
| 10 | A | 34 | d | |
| 11 | В | 35 | f | |
| 12 | С | 36 | h | |
| 13 | D | 37 | n | |
| 14 | E | 38 | r | |
| 15 | F | 39 | t | |
| 16 | G | 40 | v | |
| 17 | Н | 41 | ١ | |
| 18 | J | 42 | ? | |
| 19 | K | 43 | { | |
| 20 | L | 44 | } | |
| 21 | М | 45 | < | |
| 22 | N | 46 | > | |
| 23 | Р | | | |

Table 2: Lists for encoding and decoding of marking.

13 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

| ramp rate | ≤ 3 K/s | |
|--------------------------------------|--|--|
| preheat | 125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s | |
| <i>T</i> > 220 °C | 30 s to 70 s | |
| <i>T</i> > 230 °C | min. 10 s | |
| <i>T</i> > 245 °C | max. 20 s | |
| <i>T</i> ≥ 255 °C | _ | |
| peak temperature T_{peak} | 250 °C +0/-5 °C | |
| wetting temperature T _{min} | 230 °C +5/-0 °C for 10 s ± 1 s | |
| cooling rate | ≤ 3 K/s | |
| soldering temperature T | measured at solder pads | |
| | | |

 Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

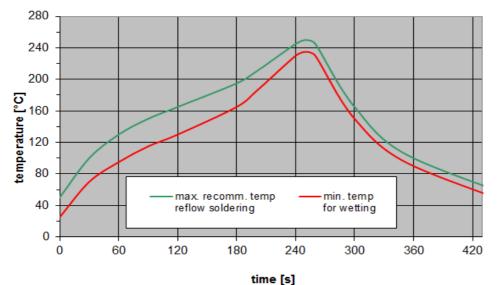


Figure 12: Recommended reflow profile for convection and infrared soldering – lead-free solder.

14 Annotations

14.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

14.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

14.3 Ordering codes and packing units

| Ordering code | Packing unit |
|-----------------|--------------|
| B39941B9630P810 | 5000 pcs |

Table 4: Ordering codes and packing units.

15 Cautions and warnings

15.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under <u>www.rf360jv.com/orderingcodes</u>.

15.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

15.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

15.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Dimensions do not include burrs.

Projection method

Unless otherwise specified first-angle projection is applied.

16 Important notes

The following applies to all products named in this publication:

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